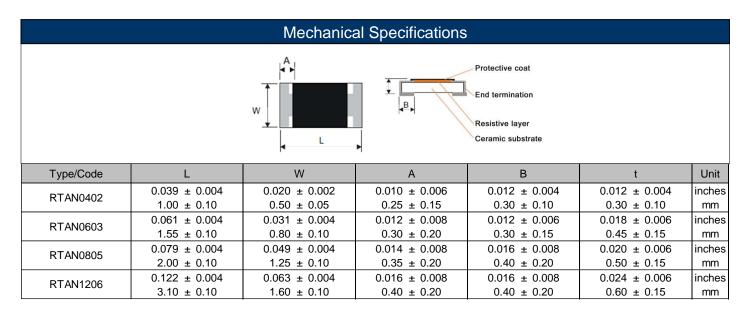
RTAN Series Tantalum Nitride Thin Film Chip Resistor

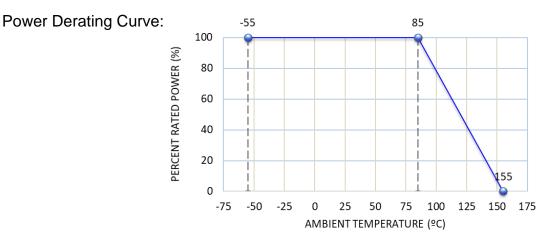
Features:

- Self-passivating technology is impervious to moisture
- Sulfur resistant (per ASTM B809-95 humid vapor test)
- Meets or exceeds 85°C / 85% R.H. at 10% rated power humidity test
- RoHS compliant, REACH compliant, lead free, and halogen free
- AEC-Q200 compliant

Electrical Specifications							
Type/Code	Power Rating (W) @ 85°C	Maximum Working	Maximum Overload	TCR (ppm/⁰C)	Ohmic Range (Ω) and Tolerance		
		Voltage (V) ⁽¹⁾ Voltage (V	Voltage (V)		0.05%, 0.1%, 0.25%, 0.5%, 1%		
RTAN0402	0.063	50	100		40.2 - 34.8K		
RTAN0603	0.15	75	150	± 10, ± 15, ± 25, ± 50	40.2 - 130K		
RTAN0805	0.2	100	200	\pm 10, \pm 15, \pm 25, \pm 50	10 - 348K		
RTAN1206	0.4	200	400		10 - 1M		

(1) Lesser of $\sqrt{(P^*R)}$ or maximum working voltage.







Stackpole Electronics, Inc. Resistive Product Solutions

RTAN Series

Tantalum Nitride Thin Film Chip Resistor

Resistive Product Solutions

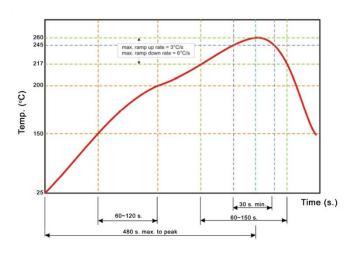
Performance Characteristics							
Test	Test Method	Test Specification Test Condition					
-			DC resistance values measurement Temperature Coefficient of Resistance (TCR) Natural resistance change per change in degree centigrade				
Electrical Characteristics	IEC-60115-1 4.8	Within the specified tolerance	$\frac{R_2 - R_1}{R_1 (t_2 - t_1)} \times 10^6 (\text{ppm/°C}) t_1: 20^\circ\text{C} + 5^\circ\text{C} / -1^\circ\text{C}$				
			R1: Resistance at reference temperature (20°C +5°C / -1°C) R2: Resistance at test temperature (-55°C or +125°C)				
Short Time Overload	IEC-60115-1 4.13	Δ R/R max. ± (0.1% + 0.02Ω)	Permanent resistance change after a 5 second application of a voltage 2.5 times RCWV or the maximum overload voltage specified in the above list, whichever is less.				
Resistance to Soldering Heat	AEC-Q200-15	No visible damage Δ R/R max. ± (0.1% + 0.02 Ω)	Un-mounted chips completely immersed for 10 ± 1 second in a SAC solder bath at 260°C ± 5°C				
Solderability	IEC-60068-2-58	Good tinning (>95% covered) No visible damage	Un-mounted chips completely immersed for 2 ± 0.5 seconds in a SAC solder bat at $235^{\circ}C \pm 5^{\circ}C$				
Thermal Shock	MIL-STD-202 Method 107	No visible damage $\Delta R/R$ max. ± (0.1%+0.02 Ω)	Test -55°C to 125°C / dwell time 15 minutes/max. transfer time 20 seconds 1000 cycles				
Biased Humidity	AEC-Q200-7	Δ R/R max. ± (0.1% + 0.02Ω)	1000 +48 / -0 hours, loaded with 10% rated power in humidity chamber controller at +85°C / 85% R.H.				
Load Life	IEC-60115-1 4.25	Δ R/R max. ± (0.1% + 0.02Ω)	1000 +48 / -0 hours, loaded with RCWV or Vmax in chamber controller 85°C ± 2°C, 1.5 hours ON and 0.5 hours OFF				
High Temperature Load Life	AEC-Q200-8 MIL-STD-202-108	Δ R/R max. ± (0.1% + 0.02Ω)	1000 hours at 125°C ± 2°C, loaded with rated power continuously				
High Temperature Exposure	AEC-Q200-3	Δ R/R max. ± (0.1% + 0.02Ω)	1000 hours at 125°C, unpowered				
Moisture Resistance	$M_{\rm H}$ -STD-202 A R/R may + (0.1% + 0.020)		65ºC ± 2°C, 80% ~ 100% R.H., 10 cycles, 24 hours/cycle				
Mechanical Shock	MIL-STD-202 Method 213	Δ R/R max. ± (0.1% + 0.02Ω)	1/2 Sine Pulse / 150g Peak / Velocity 15.4 foot/second				
Vibration	ration MIL-STD-202 Method 204 Δ R/R max. ± (0.1% + 0.02Ω)		5g for 20 minutes, 12 cycles each of 3 orientations				
Terminal Strength	AEC-Q200-6	No breaking	1 kg for 60 seconds				
Bending Strength	AEC-Q200-21	Δ R/R max. ± (0.1% + 0.02Ω)	Bending 2 mm for 60 seconds				
Flower of Sulfur	ASTM-B809-95	0402: Δ R/R max. ± (0.2% + 0.02Ω) all others: Δ R/R max. ± (0.1% + 0.02Ω)	105 \pm 2°C, duration 1000 hours				

Recommended storage conditions: Temperature 5°C to 40°C. Humidity: 20% to 70% R.H. Operating temperature range is -55°C to 155°C

Soldering Condition:

The robust construction of chip resistors allows them to be completely immersed in a solder bath of 260°C for 10 seconds. Therefore, it is possible to mount surface mount resistors on one side of a PCB and other discrete components on the reverse (mixed PCBs).

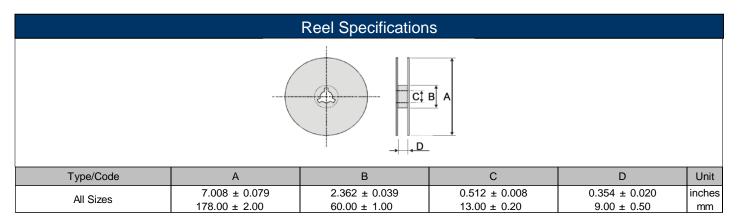
Surface mount resistors are tested for solderability at 235°C during 2 seconds within lead-free solder bath. The test condition for no leaching is 260°C for 30 seconds. Typical examples of soldering profile and condition that provide reliable joints without any damage are given on the picture on the right.



RTAN Series

Tantalum Nitride Thin Film Chip Resistor

Recommended Solder Pad								
$ \begin{array}{c} \\ \hline \\ \\ \\ \\ \\ \hline \\$								
Type/Code	A	В	С	Unit				
	0.059	0.020	0.020	inches				
RTAN0402	1.50	0.50	0.50	mm				
DTANOCOO	0.083	0.035	0.024	inches				
RTAN0603	2.10	0.90	0.60	mm				
DTANODOS	0.102	0.047	0.028	inches				
RTAN0805	2.60	1.20	0.70	mm				
DTANKOOG	0.150	0.079	0.035	inches				
RTAN1206	3.80	2.00	0.90	mm				

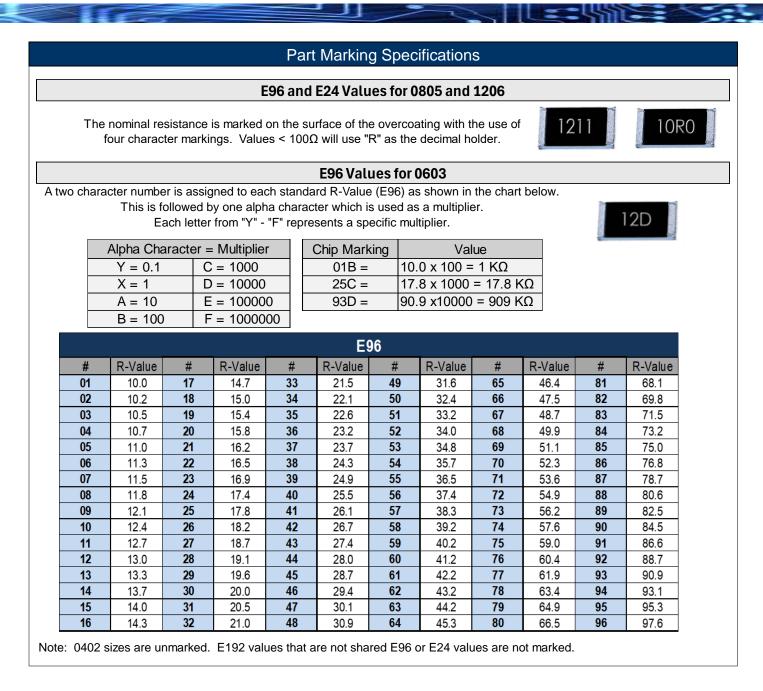


	Packaging Specifications – Paper Tape									
$\begin{array}{c} \\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\$										
Type/Code	А	В	W	F	E	P1	PO	D	Т	Unit
RTAN0402	0.047 ± 0.004	0.028 ± 0.004	0.315 ± 0.012	0.138 ± 0.008	0.069 ± 0.004	0.079 ± 0.004	0.157 ± 0.004	0.059 ± 0.004	0.016 ± 0.002	inches
	1.20 ± 0.10	0.70 ± 0.10	8.00 ± 0.30	3.50 ± 0.20	1.75 ± 0.10	2.00 ± 0.10	4.00 ± 0.10	1.50 ± 0.10	0.40 ± 0.05	mm
RTAN0603	0.075 ± 0.008	0.043 ± 0.008	0.315 ± 0.012	0.138 ± 0.008	0.069 ± 0.004	0.157 ± 0.004	0.157 ± 0.004	0.059 ± 0.004	0.026 ± 0.002	inches
	1.90 ± 0.20	1.10 ± 0.20	8.00 ± 0.30	3.50 ± 0.20	1.75 ± 0.10	4.00 ± 0.10	4.00 ± 0.10	1.50 ± 0.10	0.65 ± 0.05	mm
RTAN0805	0.094 ± 0.008	0.065 ± 0.008	0.315 ± 0.012	0.138 ± 0.008	0.069 ± 0.004	0.157 ± 0.004	0.157 ± 0.004	0.059 ± 0.004	0.039 max.	inches
	2.40 ± 0.20	1.65 ± 0.20	8.00 ± 0.30	3.50 ± 0.20	1.75 ± 0.10	4.00 ± 0.10	4.00 ± 0.10	1.50 ± 0.10	1.00 max.	mm
RTAN1206	0.142 ± 0.008	0.079 ± 0.008	0.315 ± 0.012	0.138 ± 0.002	0.069 ± 0.004	0.157 ± 0.004	0.157 ± 0.004	0.059 ± 0.004	0.039 max.	inches
	3.60 ± 0.20	2.00 ± 0.20	8.00 ± 0.30	3.50 ± 0.05	1.75 ± 0.10	4.00 ± 0.10	4.00 ± 0.10	1.50 ± 0.10	1.00 max.	mm

Tantalum Nitride Thin Film Chip Resistor

Stackpole Electronics, Inc.

Resistive Product Solutions



RoHS Compliance

Stackpole Electronics has joined the worldwide effort to reduce the amount of lead in electronic components and to meet the various regulatory requirements now prevalent, such as the European Union's directive regarding "Restrictions on Hazardous Substances" (RoHS 3). As part of this ongoing program, we periodically update this document with the status regarding the availability of our compliant components. All our standard part numbers are compliant to EU Directive 2011/65/EU of the European Parliament as amended by Directive (EU) 2015/863/EU as regards the list of restricted substances.

RoHS Compliance Status									
Standard Product Series	Description	Package / Termination Type	Standard Series RoHS Compliant	Lead-Free Termination Composition	Lead-Free Mfg. Effective Date (Std Product Series)	Lead-Free Effective Date Code (YY/WW)			
RTAN	Tantalum Nitride Thin Film Chip Resistor	SMD	YES	100% Matte Sn	Always	Always			

"Conflict Metals" Commitment

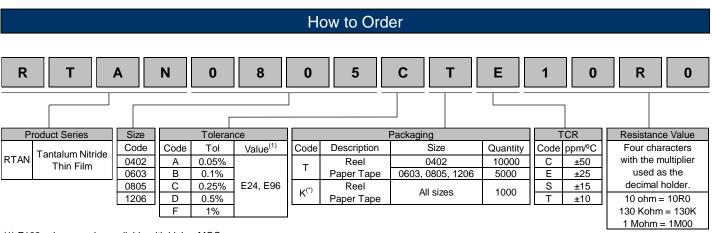
We at Stackpole Electronics, Inc. are joined with our industry in opposing the use of metals mined in the "conflict region" of the eastern Democratic Republic of the Congo (DRC) in our products. Recognizing that the supply chain for metals used in the electronics industry is very complex, we work closely with our own suppliers to verify to the extent possible that the materials and products we supply do not contain metals sourced from this conflict region. As such, we are in compliance with the requirements of Dodd-Frank Act regarding Conflict Minerals.

Compliance to "REACH"

We certify that all passive components supplied by Stackpole Electronics, Inc. are SVHC (Substances of Very High Concern) free and compliant with the requirements of EU Directive 1907/2006/EC, "The Registration, Evaluation, Authorization and Restriction of Chemicals", otherwise referred to as REACH. Contact us for complete list of REACH Substance Candidate List.

Environmental Policy

It is the policy of Stackpole Electronics, Inc. (SEI) to protect the environment in all localities in which we operate. We continually strive to improve our effect on the environment. We observe all applicable laws and regulations regarding the protection of our environment and all requests related to the environment to which we have agreed. We are committed to the prevention of all forms of pollution.



(1) E192 values may be available with higher MOQ

(*) MOQ for K packaging is 5000 pieces